Functional Safety Information

TXV0108-Q1
Functional Safety FIT Rate, FMD and Pin FMA

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Trademarks

1 Overview

This document contains information for TXV0108-Q1 (VQFN package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.

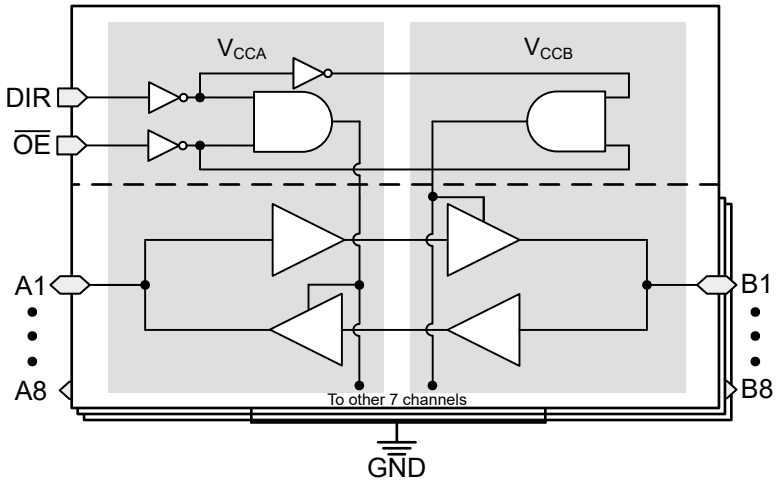

Figure 1-1. Functional Block Diagram

TXV0108-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for VQFN package of TXV0108-Q1 based on industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)
Total Component FIT Rate	11
Die FIT Rate	2
Package FIT Rate	9

The failure rate and mission profile information in Table 2-2 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 32 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
5	CMOS Analog switch, Bus Interface	5 FIT	55°C

The reference FIT rate and reference Virtual T_J (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for TXV0108-Q1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
Driver HiZ, no output	31%
Functional fail (voltage, timing; out of specification)	33%
Driver stuck at fault high	14%
Driver stuck at fault low	14%
Driver stuck at undetermined state	8%

4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the TXV0108-Q1 (VQFN package). The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to supply (see Table 4-5 and Table 4-6)

Table 4-2 through Table 4-6 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

Table 4-1. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Pin Diagram (VQFN) Package shows the TXV0108-Q1 pin diagram for the VQFN package. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the TXV0108-Q1 data sheet.

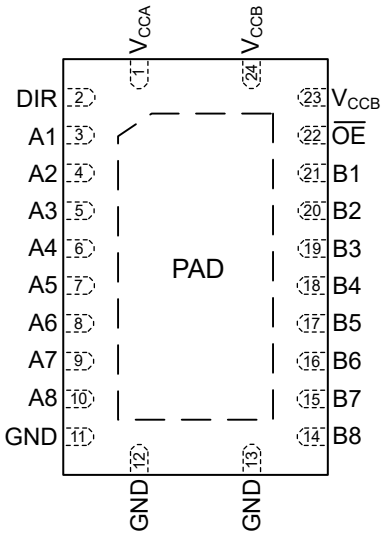

Figure 4-1. Pin Diagram (VQFN) Package

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to supply (see Table 4-5 and Table 4-6)

Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VCCA	1	GND short to VCC, device will be bypassed - may cause system damage, but not device damage	B
DIR	2	Direction control will fixed, B --> A direction.	B
A1 - A8	3 to 10	If configured as an output then damage is possible. If configured as input, no damage, but output will not switch.	A
GND	11 to 13	Normal operation.	D
B8 - B1	14 to 21	If configured as an output then damage is possible. If configured as input, no damage, but output will not switch.	A
OE (active low)	22	Outputs will remain enabled.	B
VCCB	23 to 24	GND short to VCC, device will be bypassed - may cause system damage, but not device damage.	B

Table 4-3. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VCCA	1	Device will not be powered.	B
DIR	2	Pin is floating which can cause excessive current.	A
A1 - A8	3 to 10	If configured as output, normal operation. If configured as input, pin is floating which can cause excessive current.	A
GND	11 to 13	Device will not be powered.	B
B8 - B1	14 to 21	If configured as output, normal operation. If configured as input, pin is floating which can cause excessive current.	A
OE (active low)	22	Pin is floating which can cause excessive current and cause the outputs to switch between enabled and disabled.	B
VCCB	23 to 24	Device will not be powered.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
VCCA	1	DIR	Direction control will fixed, B --> A direction.	B
DIR	2	A1	If DIR is LOW, A1 will be an output and damage is possible. If DIR is HIGH, A1 will be an input and drive the output B1 HIGH.	A
A(n)	3 to 9	A(n+1)	If A(n) and A(n+1) are configured as outputs then damage is possible. If configured as inputs, both bits will have the same value always	A
A8	10	GND	If A8 is configured as an output then damage is possible. If configured as input, output B8 will be fixed LOW.	A
GND	11 to 12	GND	Normal Operation.	D
GND	13	B8	If B8 is configured as an output then damage is possible. If configured as input, output A8 will be fixed LOW.	A
B(n)	14 to 20	B(n+1)	If B(n) and B(n+1) are configured as outputs then damage is possible. If configured as inputs, both bits will have the same value always.	A
B1	21	VCCB	If B1 is configured as an output then damage is possible. If configured as an input, no damage, but output A1 will remain HIGH.	A
VCCB	23 to 24	VCCB	Normal Operation.	D
VCCB	24	VCCA	VCCB short to VCCA, device will be bypassed - may cause system damage, but not device damage.	B

Table 4-5. Pin FMA for Device Pins Short-Circuited to supply VCCA

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VCCA	1	Normal Operation.	D
DIR	2	Direction control will fixed, B --> A direction.	B
A1 - A8	3 to 10	If configured as an output then damage is possible. If configured as input, no damage, but output will not switch.	A
GND	11 to 13	GND short to VCC, device will be bypassed. This can cause system damage, but not device damage.	B
B8 - B1	14 to 21	If configured as an output then damage is possible. If configured as input, damage is possible if VIH/VIL is not met.	A
OE (active low)	22	Outputs will remain disabled.	B
VCCB	23 to 24	VCCB short to VCCA, device will be bypassed. This can cause system damage, but not device damage.	B

Table 4-6. Pin FMA for Device Pins Short-Circuited to supply VCCB

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
VCCA	1	VCCB short to VCCA, device will be bypassed. This can cause system damage, but not device damage.	B
DIR	2	If VCCA > VCCB, then the direction control will fix A-->B, If VCCA < VCCB, damage is possible if VIH/VIL is not met.	A
A1 - A8	3 to 10	If configured as an output then damage is possible. If configured as input, damage is possible if VIH/VIL not met.	A
GND	11 to 13	GND short to VCC, device will be bypassed. This can cause system damage, but not device damage.	B
B8 - B1	14 to 21	If configured as an output then damage is possible. If configured as input, no damage, but output will not switch.	A
OE (active low)	22	If VCCA > VCCB, then the outputs will remain disabled, If VCCA < VCCB, damage is possible if VIH/VIL is not met.	A
VCCB	23 to 24	Normal operation.	D

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